CDIP / CerDIP

data sheet

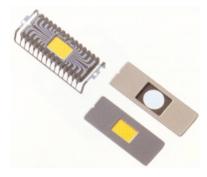
Ceramic Dual-Inline Package (CDIP / CerDIP)

Amkor Technology is committed to continuing to service this long established standard industry package. The Amkor Technology CDIP capability provides a wide range of lead counts and body sizes. The CDIP is a hermetic package consisting of two pieces of dry pressed ceramic surrounding a "DIP formed" leadframe. The ceramic / LF / ceramic system is held together hermetically by frit glass reflowed at temperatures between 400° - 460° Centigrade.

Applications:

Along with the other standard industry packages, the CDIP has a proven track record and is still being used by semiconductor technologies such as: Digital to Analog converters, EPROMS, Air bag sensors, Logic, Memory, Microcontrollers, and Video controllers. Some end applications are: Military electronics, Commercial electronics, Automotive and Telecommunications.

Features:	The CDIP offers a variety of features:
	 300 mil package body width with lead counts from 8L to 28L 400 mil package body width with lead counts of 22L & 24L 600 mil package body width with lead counts from 24L to 40L 100 mil lead pitch High thermal conductive ceramic Matte Tin lead finish JEDEC standard compliant Wide selection of available cavity sizes to meet most die size needs Commercial or full Military flows



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